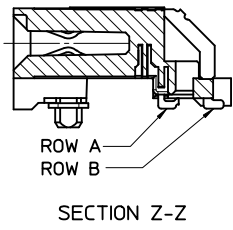
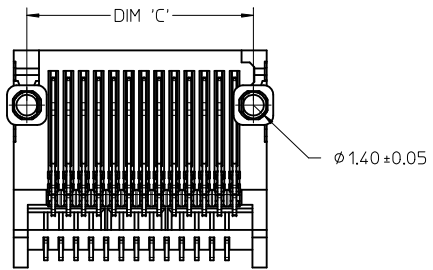
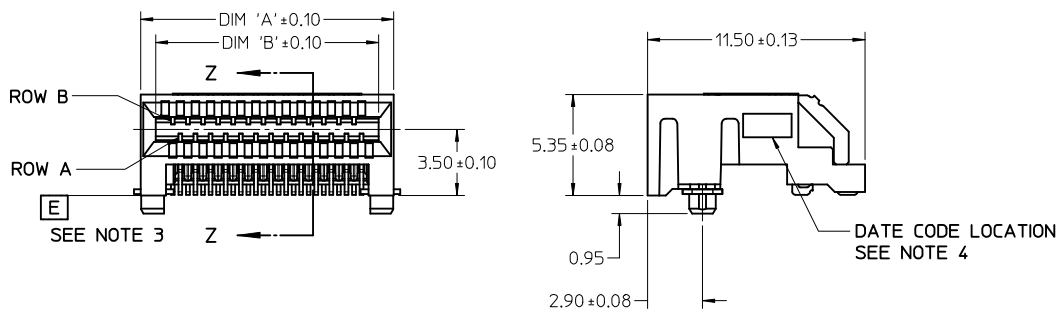
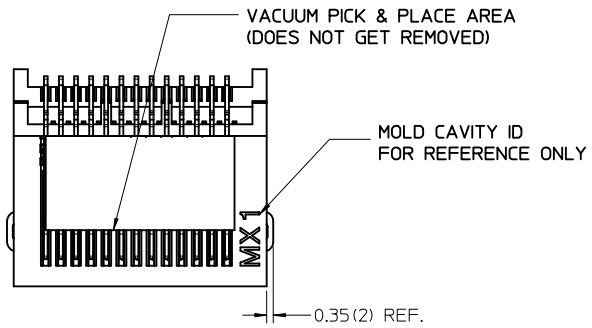
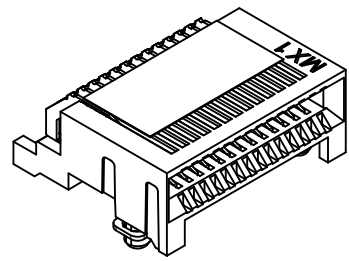


CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0101	OPTION 1	13.40	11.80	12.00
26	75586-0102	OPTION 2	13.40	11.80	12.00
38	75586-0103	OPTION 1	18.20	16.60	16.80
38	75586-0104	OPTION 2	18.20	16.60	16.80
68	75586-0105	OPTION 1	30.20	28.60	28.80
68	75586-0106	OPTION 2	30.20	28.60	28.80



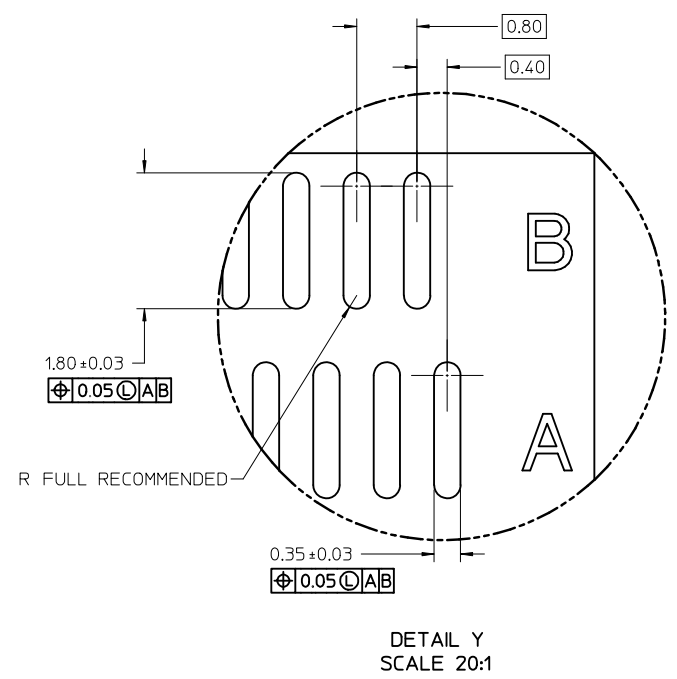
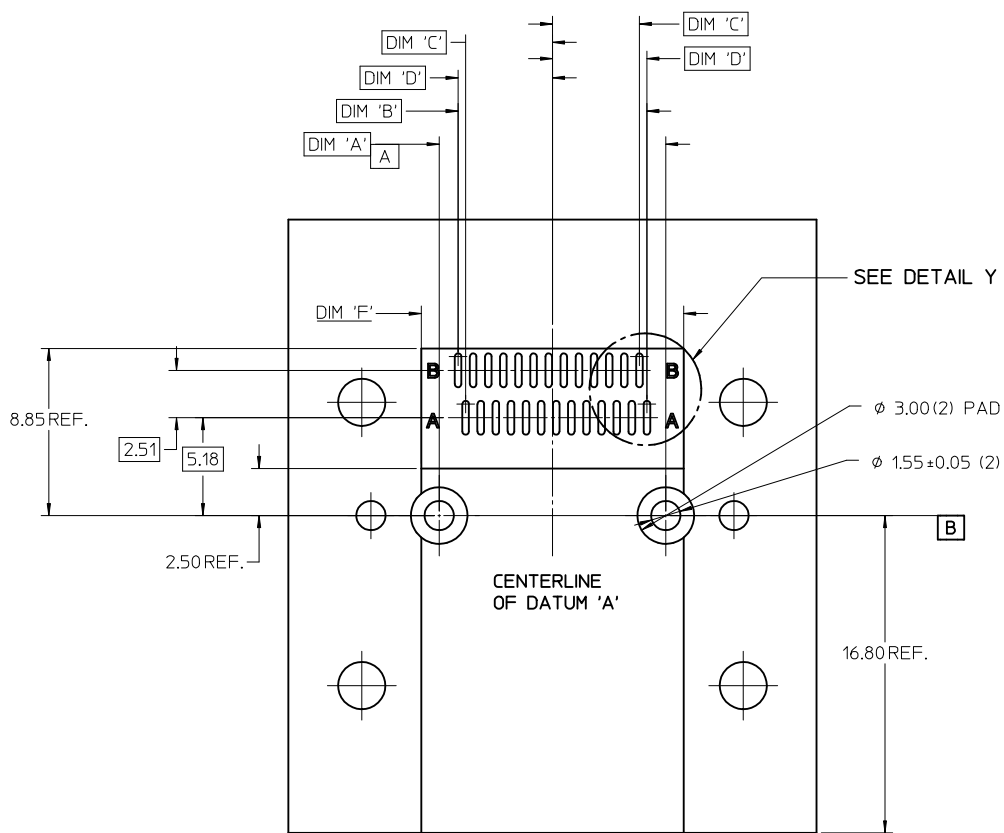
- NOTES
- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
 - PLATING:
OPTION 1
CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 μm TIN OVER 2.54 μm MIN NICKEL.
OPTION 2
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL
SOLDER AREA - 2.54 - 5.09 μm TIN OVER 2.54 μm MIN NICKEL.
 - TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)
 - DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
 - CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
 - TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)
 - TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)
 - PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002
 - CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001
 - THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



iPass™ IS A TRADEMARK OF MOLEX

UPDATE VIEW SETS IEC NO: UCP2012-3302 IDRWN: GONZALEZ01 2012/04/20 CHKD: MCCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm	INCH	DRAWN BY	DATE	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex DOCUMENT NO. SD-75586-005 SHEET NO. 1 OF 6			
		3 PLACES ± --- ± ---			CHECKED BY	DATE				
		2 PLACES ± 0.13 ± ---			APPROVED BY	DATE				
1 PLACE ± 0.25 ± ---			DATE	DATE						
0 PLACE ± ±			MATERIAL NO.							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1/2°		SEE CHART						
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

MOTHERBOARD FOOTPRINT RECOMMENDATION

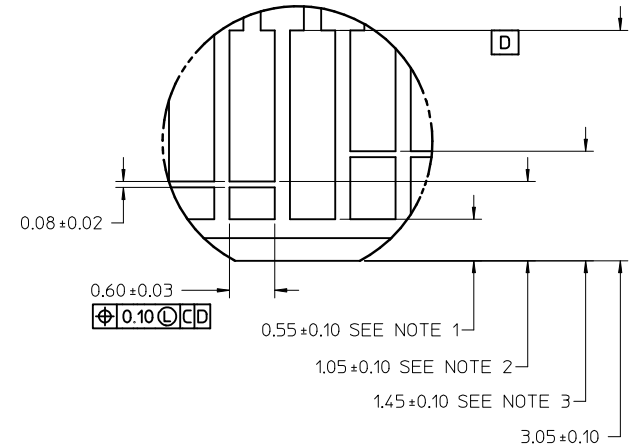
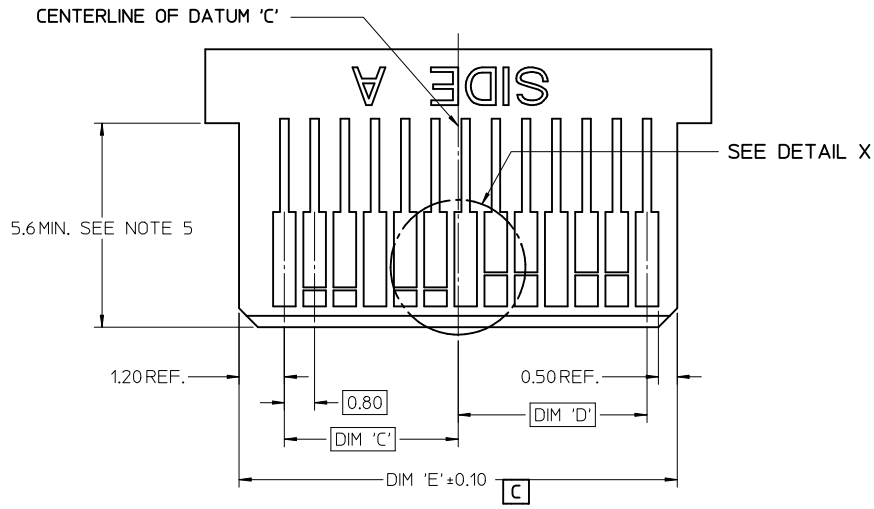


NOTES:
 1. SEE 74540 OR 74548 SERIES FOR GUIDE FRAME FOOT PRINT AND KEEP OUT AREA.

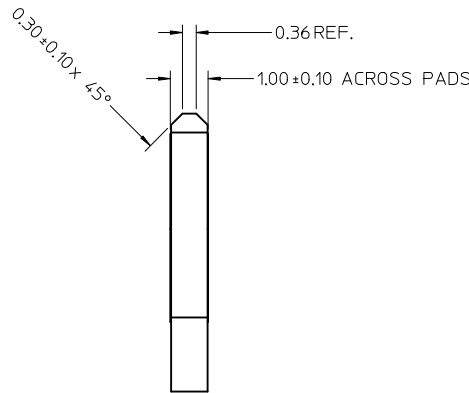
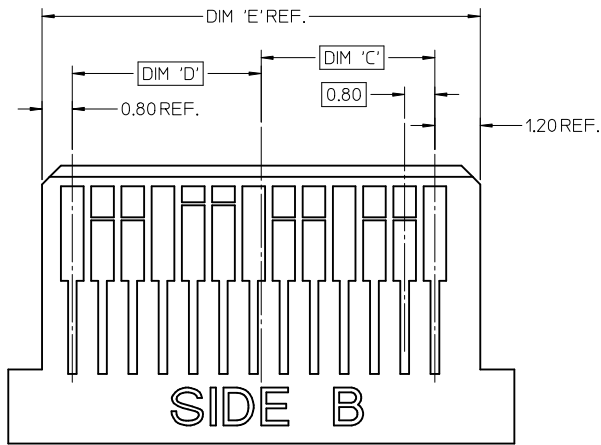
CIRCUIT SIZE	TERM/SIDE 'N'	DIMENSIONS					
		PEG TO PEG	FIRST PAD TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH	CONNECTOR WIDTH
		DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'
26	13	12.00	10.00	4.60	5.00	11.60	13.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1 EC NO: UCP2012-3302 DRWN: GONZALEZ01 2012/04/20 CHKD: MCCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm INCH	MM ONLY	10:1	METRIC		
		4 PLACES ± --- ± ---	DRAWN BY DATE	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex DOCUMENT NO. SD-75586-005 SHEET NO. 2 OF 6			
		3 PLACES ± --- ± ---	CHECKED BY DATE				
	2 PLACES ± 0.13 ± ---	APPROVED BY DATE					
	1 PLACE ± 0.25 ± ---	MATERIAL NO.					
	0 PLACE ± ±	ANGULAR ±1/2°	SEE CHART				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

MODULE BOARD FOOTPRINT RECOMMENDATION



DETAIL X
SCALE 20:1



NOTES:

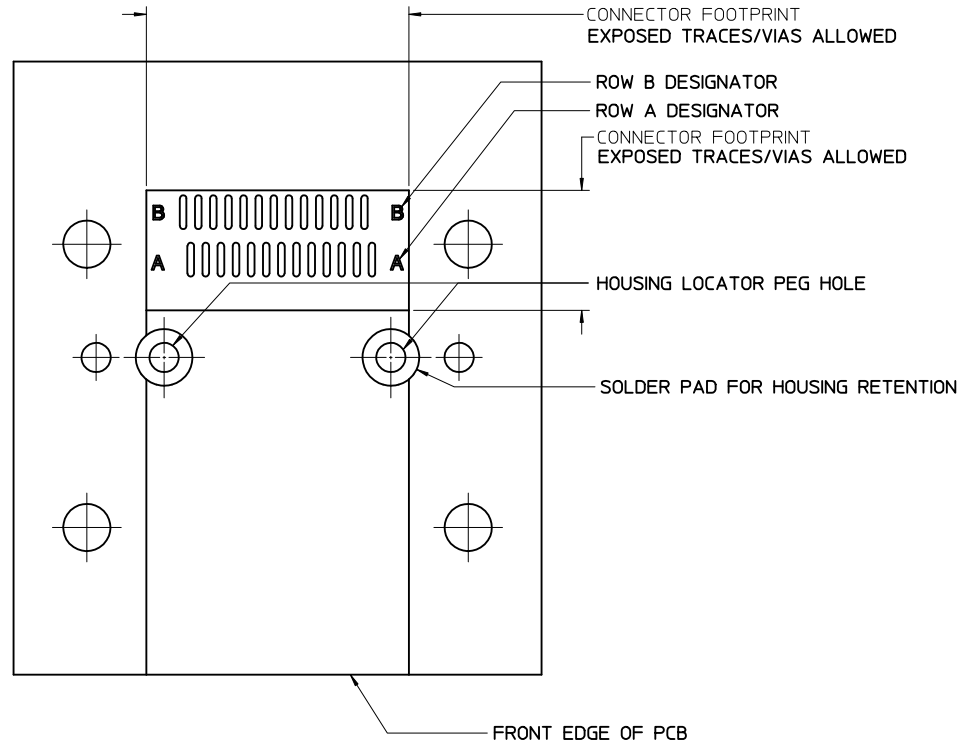
- PAD CONFIGURATION FOR FIRST MATE.
- PAD CONFIGURATION FOR SECOND MATE.
- PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS).
- FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
- MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TOUNGE.

iPass™ IS A TRADEMARK OF MOLEX

CIRCUIT SIZE	TERM/SIDE 'N'	MODULE BOARD WIDTH		
		CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH
		DIM 'C'	DIM 'D'	DIM 'E'
26	13	4.60	5.00	11.60
38	19	7.00	7.40	16.40
68	34	13.00	13.40	28.40

SEE SHEET 1 EC NO: UCP2012-3302 DRAWN: GONZALEZ01 2012/04/20 CHKD: MCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY KLANG		DATE 12/06/2006	
		4 PLACES ± --- ± ---				CHECKED BY JSWENSON		DATE 12/06/2006	
		3 PLACES ± --- ± ---				APPROVED BY MBANAKIS		DATE 12/06/2006	
2 PLACES ± 0.13 ± ---				MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
1 PLACE ± 0.25 ± ---				ANGULAR ± 1/2°		SEE CHART		SD-75586-005	
0 PLACE ± ±				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		3 OF 6	

CONNECTOR FOOTPRINT ZONE IDENTIFICATION



iPass™ IS A TRADEMARK OF MOLEX

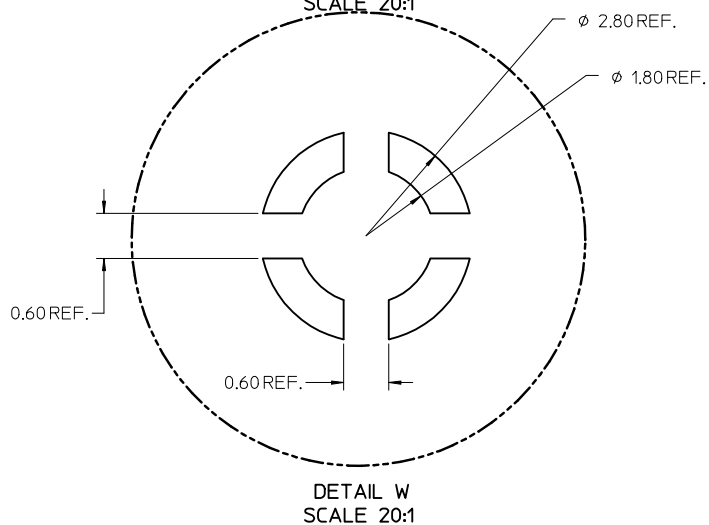
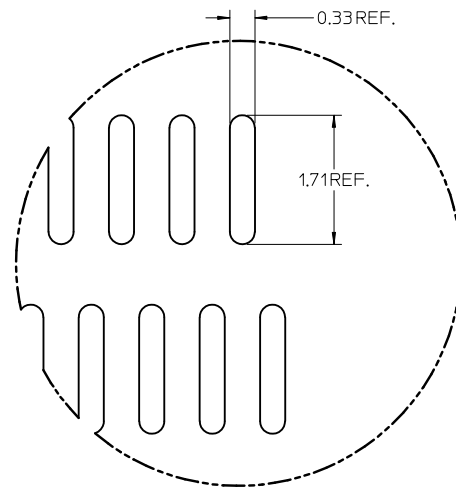
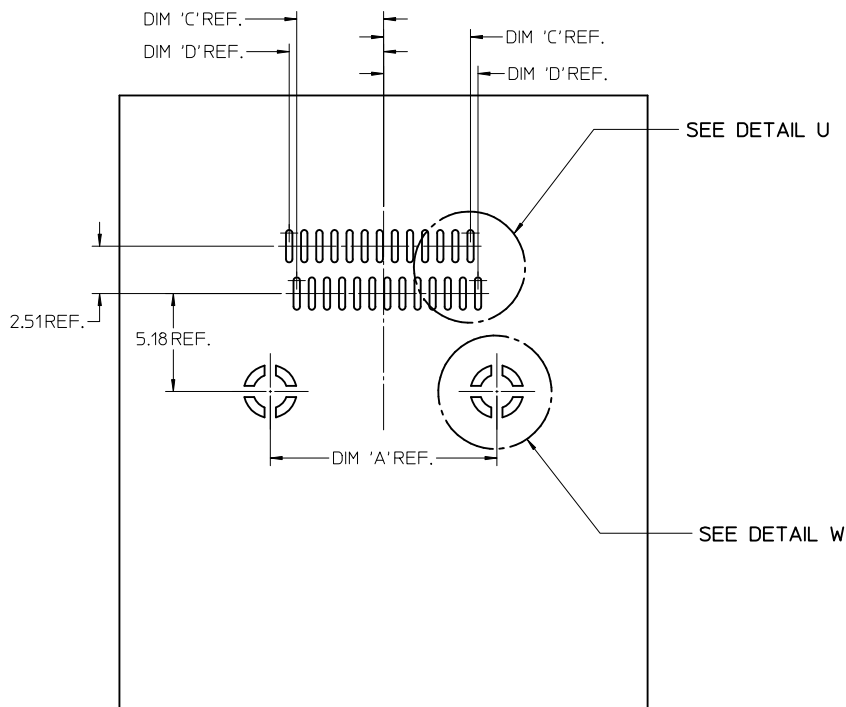
SEE SHEET 1 EC NO: UCP2012-3302 DRWN: JGONZALEZ01 2012/04/20 CHKD: MCELLELAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	▽=0	mm	INCH	DRAWN BY	DATE	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING			
	▽=0	4 PLACES ± ---	± ---	KLANG	12/06/2006				
	▽=0	3 PLACES ± ---	± ---	CHECKED BY	DATE	molex DOCUMENT NO. SD-75586-005 SHEET NO. 4 OF 6			
▽=0	2 PLACES ± 0.13	± ---	JWENSON	12/06/2006					
	1 PLACE ± 0.25	± ---	APPROVED BY	DATE	MATERIAL NO. SEE CHART				
	0 PLACE ±	±	MBANAKIS	12/06/2006					
		ANGULAR ±1/2°		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		C					
C1	REV								

NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SOLDER STENCIL RECOMMENDATION

SOLDER FOOT: ~90% OF PAD
 SOLDER RING: ~45% OF PAD

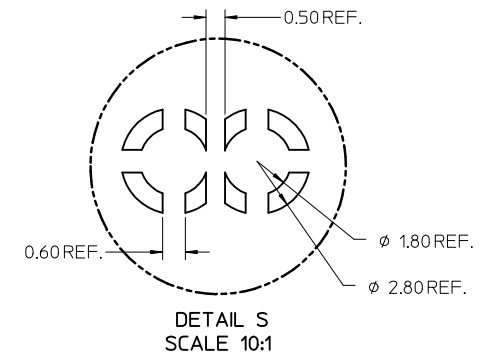
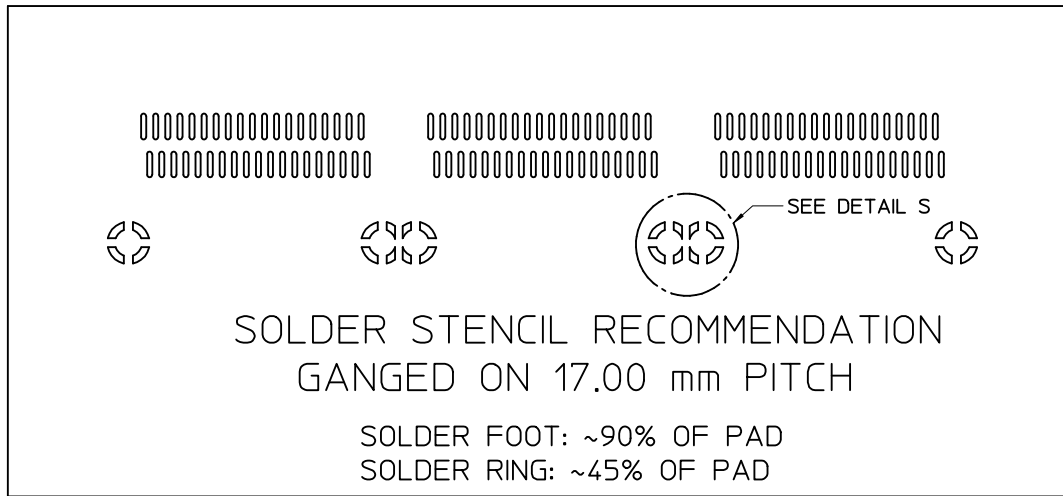
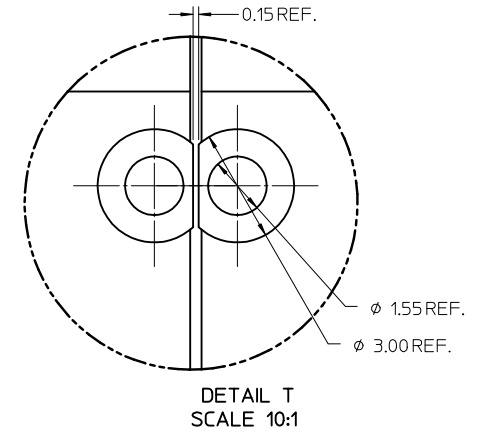
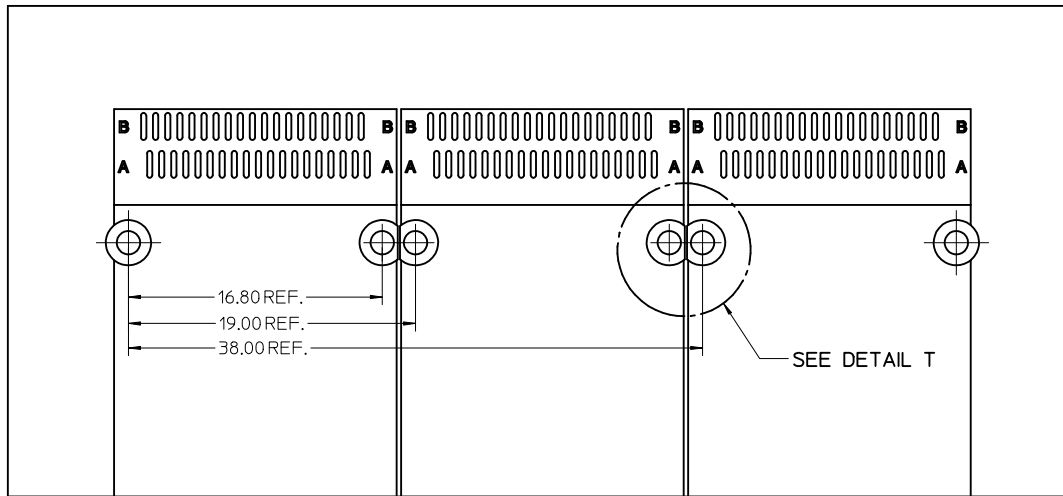


iPass™ IS A TRADEMARK OF MOLEX

CIRCUIT SIZE	TERM/SIDE 'N'	DIMENSIONS		
		DIM 'A'	DIM 'C'	DIM 'D'
26	13	12.00	4.60	5.00
38	19	16.80	7.00	7.40
68	34	26.80	13.00	13.40

SEE SHEET 1 EC NO: UCP2012-3302 DRWN: JGONZALEZ01 2012/04/20 CHKD: MCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY DATE KLANG 12/06/2006	TITLE	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex DOCUMENT NO. SD-75586-005 SHEET NO. 5 OF 6	
	▽=0	4 PLACES ± --- ± ---	CHECKED BY DATE JSWENSON 12/06/2006			
	▽=0	3 PLACES ± --- ± ---	APPROVED BY DATE MBANAKIS 12/06/2006			
▽=0	2 PLACES ± 0.13 ± ---	MATERIAL NO.				
		0 PLACE ± 0.25 ± ---	SEE CHART			
		ANGULAR ±1/2°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

38 CIRCUIT GANGED ON 19.00 mm CENTERLINE



iPass™ IS A TRADEMARK OF MOLEX

NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SEE SHEET 1 EC NO: UCP2012-3302 DRWN: JGONZALEZ01 2012/04/20 CHKD: MCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY DATE KLANG 12/06/2006	TITLE	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex DOCUMENT NO. SD-75586-005 SHEET NO. 6 OF 6	
	▽=0	4 PLACES ± --- ± ---	CHECKED BY DATE JSWENSON 12/06/2006			
	▽=0	3 PLACES ± --- ± ---	APPROVED BY DATE MBANAKIS 12/06/2006			
	2 PLACES ± 0.13 ± ---					
		1 PLACE ± 0.25 ± ---				
		0 PLACE ± ±				
		ANGULAR ±1/2°	MATERIAL NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE CHART			
			SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		